

2N3820

P-Channel General Purpose Amplifier

- This device is designed primarily for low level audio and general purpose applications with high impedance signal sources.
- Sourced from process 89.



Epitaxial Silicon Transistor

Absolute Maximum Ratings* $T_C=25$ °C unless otherwise noted

Symbol	Parameter	Ratings	Units	
V_{DG}	Drain-Gate Voltage	-20	V	
V_{GS}	Gate-Source Voltage	20	V	
I _{GF}	Forward Gate Current	10	mA	
T _{STG}	Storage Temperature Range	-55 ~ 150	°C	

^{*} This ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

$\textbf{Electrical Characteristics} \ \, \textbf{T}_{\text{C}} = 25 ^{\circ} \text{C unless otherwise noted}$

Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Units
Off Chara	Off Characteristics					
V _{(BR)GSS}	Gate-Source Breakdwon Voltage	$I_G = 10\mu A, V_{DS} = 0$	20			V
I _{GSS}	Gate Reverse Current	$V_{GS} = 10V, V_{DS} = 0$			20	nA
V _{GS} (off)	Gate-Source Cutoff Voltage	$V_{DS} = -10V, I_{D} = -10\mu A$			8.0	V
On Characteristics						
I _{DSS}	Zero-Gate Voltage Drain Current *	$V_{DS} = -10V, V_{GS} = 0$	-0.3		-15	mA
Small Signal Characteristics						
gfs	Forward Transfer Conductance	$V_{DS} = -10V, V_{GS} = 0, f = 1.0KHz$	800		5000	μmhos
C _{iss}	Input Capacitance	$V_{DS} = -10V, V_{GS} = 0, f = 1.0KHz$			32	pF
C _{rss}	Reverse Transfer Capacitance	$V_{DS} = -10V, V_{GS} = 0, f = 1.0KHz$			16	pF
Pulse Test: Pulse Width < 300ms, Duty Cycle < 2%						

Thermal Characteristics T_A=25°C unless otherwise noted

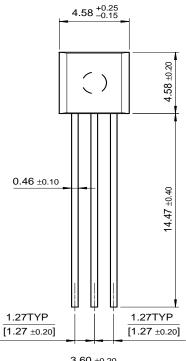
Symbol	Parameter	Max.	Units	
P _D	Total Device Dissipation	350	mW	
	Derate above 25°C	2.8	mW/°C	
$R_{\theta JC}$	Thermal Resistance, Junction to Case	125	°C/W	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	357	°C/W	

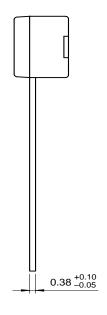
^{*} Device mounted on FR-4 PCB 1.6" × 1.6" × 0.06"

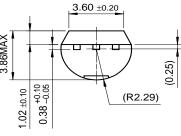
These rating are based on a maximum junction temperature of 150 degrees C.
These are steady limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

Package Dimensions

TO-92







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